Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

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**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .0085” X .0085”**

**Backside Potential: Cathode**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .024” X .024” DATE: 11/3/21**

**MFG: MOTOROLA THICKNESS .010” P/N: 1N4684**

**DG 10.1.2**

#### Rev B, 7/19/02